



DATE: 15th July, 2010

PCN #: 2017

PCN Title: Qualification of Additional Wafer Sources or Die Shrink.

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2017-I REV00

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
July 15, 2010	October 13, 2010	Discrete Semiconductors	Wafer FAB Material and Wafer Fabrication Site	2017
TITLE				
Qualification of Additional Wafer Sources or Die Shrink				
DESCRIPTION OF CHANGE				
<p>In order to assure continuity of supply, this PCN is being issued to notify customers of the qualification of Diodes FabTech (KFAB) and Diodes/Zetex (OFAB) wafer fabrication sites in addition to the currently qualified wafer fabrication site (Phenitec). Some select devices will be qualified with a smaller die size within the existing wafer fabrication site (Phenitec). Affected products are listed in the attached table.</p> <p>Full electrical characterization and high reliability testing will be completed on representative parts to ensure no change to device functionality or data sheet electrical specifications.</p> <p>There is no change to Form, Fit or Function.</p>				
IMPACT				
None.				
PRODUCTS AFFECTED				
See attached table.				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Devices to FabTech (KFAB)	Devices to FabTech (KFAB)	Devices to Zetex (OFAB)	Devices to Shrink Die in Phenitec
1N4148WT-7	PD3Z284C22-7	DMMT5401-7-F	BZT52B6V2-7-F
1N4448HLP-7	PD3Z284C24-7	DN350T05-7	BZX84B3V9-7-F
1N4448HWT-13	PD3Z284C27-7	DP350T05-7	BZX84B5V1-7-F
1N4448HWT-7	PD3Z284C2V4-7	DZT5401-13	BZX84B5V6-7-F
BAS116-7-G	PD3Z284C2V7-7		BZX84B8V2-7-F
BAS116V-7	PD3Z284C30-7		
BAS16HLP-7	PD3Z284C33-7		
BAS16LP-7	PD3Z284C36-7		
BAS16V-7	PD3Z284C39-7		
BAV116W-7-G	PD3Z284C3V0-7		
BZT52C2V0-7-F	PD3Z284C3V3-7		
BZT52C2V0S-7-F	PD3Z284C3V6-7		
BZT52C2V0T-7	PD3Z284C3V9-7		
BZT52C2V4LP-7	PD3Z284C4V3-7		
BZT52C2V4T-7	PD3Z284C4V7-7		
BZT52C2V7LP-7			
BZT52C2V7T-7			
BZT52C3V0LP-7			
BZT52C3V0T-7			
BZT52C3V0T-7-G			
BZT52C3V0T-7-G			
BZT52C3V3LP-7			
BZT52C3V3T-7			
BZT52C3V6LP-7			
BZT52C3V6T-7			
BZT52C3V9LP-7			
BZT52C3V9T-7			
BZT52C4V3LP-7			
BZT52C4V3T-7			
BZT52C4V7LP-7			
BZT52C4V7T-7			
BZT52C5V1T-7			
BZX84C2V4-7-G			
MMBD4448V-7			
MMBZ5225BTS-7-F			
PD3SD2580-7			
PD3Z284C13-7			
PD3Z284C15-7			
PD3Z284C16-7			
PD3Z284C18-7			
PD3Z284C20-7			